

EconoDUAL™3 Modul mit Trench/Feldstopp IGBT4 und Emitter Controlled 4 Diode und PressFIT / NTC
EconoDUAL™3 module with Trench/Fieldstop IGBT4 and Emitter Controlled 4 diode and PressFIT / NTC



$V_{CES} = 1200V$
 $I_{C\ nom} = 600A / I_{CRM} = 1200A$

Typische Anwendungen

- Elektro- und Hybridnutzfahrzeuge
- Hochleistungsumrichter
- Motorantriebe
- Servoumrichter

Elektrische Eigenschaften

- Niedriges V_{CEsat}
- $T_{vj\ op} = 150^{\circ}C$
- V_{CEsat} mit positivem Temperaturkoeffizienten

Mechanische Eigenschaften

- Hohe Last- und thermische Wechselfestigkeit
- Hohe Leistungsdichte
- Isolierte Bodenplatte
- PressFIT Verbindungstechnik

Typical Applications

- Construction, Commercial and Agriculture Vehicles
- High Power Converters
- Motor Drives
- Servo Drives

Electrical Features

- Low V_{CEsat}
- $T_{vj\ op} = 150^{\circ}C$
- V_{CEsat} with positive Temperature Coefficient

Mechanical Features

- High Power and Thermal Cycling Capability
- High Power Density
- Isolated Base Plate
- PressFIT Contact Technology

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

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IGBT, Wechselrichter / IGBT, Inverter
Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1200	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_C = 100^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$ $T_C = 25^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	$I_{C\text{ nom}}$ I_C	600 950	A A
Grenzeffektivstrom der Modul DC-Kontakte Maximum RMS module DC-terminal current	$T_{\text{Terminal}} \leq 105^{\circ}\text{C}, T_C = 112^{\circ}\text{C}$ $T_{\text{Terminal}} \leq 105^{\circ}\text{C}, T_C = 139^{\circ}\text{C}$	I_{TRMS}	415 370	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_p = 1\text{ ms}$	I_{CRM}	1200	A
Gesamt-Verlustleistung Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	P_{tot}	3350	W
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 600\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 600\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 600\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,75 2,00 2,05	2,10	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 23,0\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	5,20	5,80	6,40 V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		Q_G	4,40		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$	1,2		Ω
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	37,0		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	2,05		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1200\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{CES}		3,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		400	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 600\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{on}} = 0,51\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$	0,15 0,17 0,17		μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 600\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{on}} = 0,51\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,05 0,06 0,06		μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 600\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{off}} = 0,51\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$	0,38 0,47 0,50		μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 600\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{off}} = 0,51\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,07 0,11 0,12		μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 600\text{ A}, V_{CE} = 600\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 8700\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{G\text{on}} = 0,51\ \Omega, V_{\text{clamp, GE}} = 18\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	18,0 40,5 48,5		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 600\text{ A}, V_{CE} = 600\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 3300\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{G\text{off}} = 0,51\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	45,0 70,0 78,0		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 800\text{ V}$ $V_{\text{CEmax}} = V_{\text{CES}} - L_{\text{SCE}} \cdot di/dt$ $t_p \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		I_{SC}	2700		A
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		R_{thJC}		0,0450	K/W

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Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$	R_{thCH}		0,0340		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions		$T_{\text{vj op}}$	-40		150	°C

Diode, Wechselrichter / Diode, Inverter

Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{\text{vj}} = 25^\circ\text{C}$	V_{RRM}		1200		V
Dauergleichstrom Continuous DC forward current		I_{F}		600		A
Periodischer Spitzenstrom Repetitive peak forward current	$t_{\text{p}} = 1 \text{ ms}$	I_{FRM}		1200		A
Grenzlastintegral I^2t - value	$V_{\text{R}} = 0 \text{ V}, t_{\text{p}} = 10 \text{ ms}, T_{\text{vj}} = 125^\circ\text{C}$ $V_{\text{R}} = 0 \text{ V}, t_{\text{p}} = 10 \text{ ms}, T_{\text{vj}} = 150^\circ\text{C}$	I^2t		35000 30500		A ² s A ² s

Charakteristische Werte / Characteristic Values

				min.	typ.	max.	
Durchlassspannung Forward voltage	$I_{\text{F}} = 600 \text{ A}, V_{\text{GE}} = 0 \text{ V}$ $I_{\text{F}} = 600 \text{ A}, V_{\text{GE}} = 0 \text{ V}$ $I_{\text{F}} = 600 \text{ A}, V_{\text{GE}} = 0 \text{ V}$	$T_{\text{vj}} = 25^\circ\text{C}$ $T_{\text{vj}} = 125^\circ\text{C}$ $T_{\text{vj}} = 150^\circ\text{C}$	V_{F}		1,90 1,85 1,80	2,30	V V V
Rückstromspitze Peak reverse recovery current	$I_{\text{F}} = 600 \text{ A}, -di_{\text{F}}/dt = 8700 \text{ A}/\mu\text{s} (T_{\text{vj}}=150^\circ\text{C})$ $V_{\text{R}} = 600 \text{ V}$ $V_{\text{GE}} = -15 \text{ V}$	$T_{\text{vj}} = 25^\circ\text{C}$ $T_{\text{vj}} = 125^\circ\text{C}$ $T_{\text{vj}} = 150^\circ\text{C}$	I_{RM}		495 615 640		A A A
Sperrverzögerungsladung Recovered charge	$I_{\text{F}} = 600 \text{ A}, -di_{\text{F}}/dt = 8700 \text{ A}/\mu\text{s} (T_{\text{vj}}=150^\circ\text{C})$ $V_{\text{R}} = 600 \text{ V}$ $V_{\text{GE}} = -15 \text{ V}$	$T_{\text{vj}} = 25^\circ\text{C}$ $T_{\text{vj}} = 125^\circ\text{C}$ $T_{\text{vj}} = 150^\circ\text{C}$	Q_{r}		53,0 100 120		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_{\text{F}} = 600 \text{ A}, -di_{\text{F}}/dt = 8700 \text{ A}/\mu\text{s} (T_{\text{vj}}=150^\circ\text{C})$ $V_{\text{R}} = 600 \text{ V}$ $V_{\text{GE}} = -15 \text{ V}$	$T_{\text{vj}} = 25^\circ\text{C}$ $T_{\text{vj}} = 125^\circ\text{C}$ $T_{\text{vj}} = 150^\circ\text{C}$	E_{rec}		29,5 52,5 59,5		mJ mJ mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode		R_{thJC}			0,0870	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$		R_{thCH}		0,0400		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{\text{vj op}}$	-40		150	°C

NTC-Widerstand / NTC-Thermistor

Charakteristische Werte / Characteristic Values

				min.	typ.	max.	
Nennwiderstand Rated resistance	$T_{\text{C}} = 25^\circ\text{C}$		R_{25}		5,00		k Ω
Abweichung von R100 Deviation of R100	$T_{\text{C}} = 100^\circ\text{C}, R_{100} = 493 \Omega$		$\Delta R/R$	-5		5	%
Verlustleistung Power dissipation	$T_{\text{C}} = 25^\circ\text{C}$		P_{25}			20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$		$B_{25/50}$		3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$		$B_{25/80}$		3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$		$B_{25/100}$		3433		K

Angaben gemäß gültiger Application Note.
Specification according to the valid application note.

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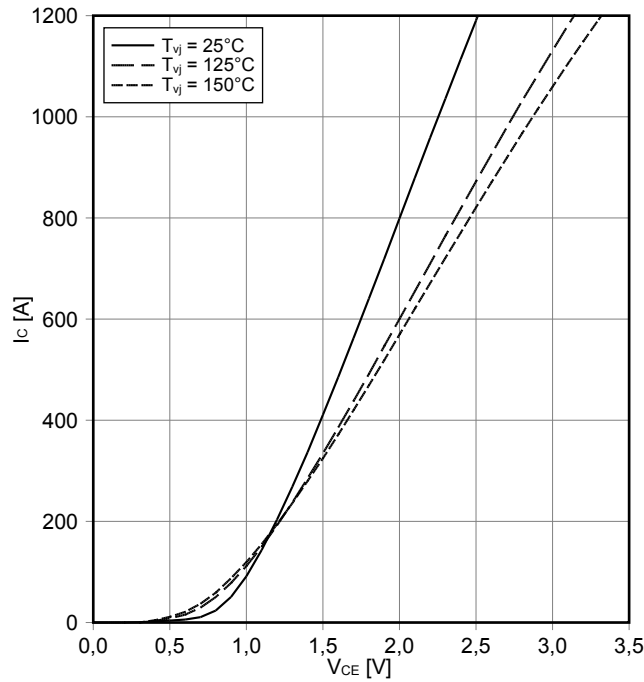
Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min	V _{ISOL}	2,5		kV
Material Modulgrundplatte Material of module baseplate			Cu		
Innere Isolation Internal isolation	Basisisolation (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		14,5 13,0		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		12,5 10,0		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 200		
			min.	typ.	max.
Modulstreuintuktivität Stray inductance module		L _{sCE}		22	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T _C = 25°C, pro Schalter / per switch	R _{CC'+EE'}		1,00	mΩ
Lagertemperatur Storage temperature		T _{stg}	-40		125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M5 - Montage gem. gültiger Applikationsschrift Screw M5 - Mounting according to valid application note	M	3,00		6,00 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	3,0	-	6,0 Nm
Gewicht Weight		G		345	g

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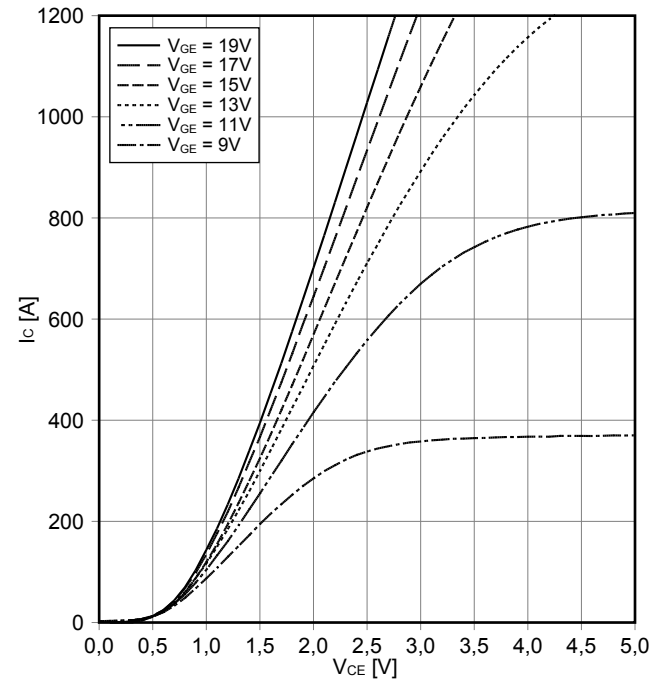
Ausgangskennlinie IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



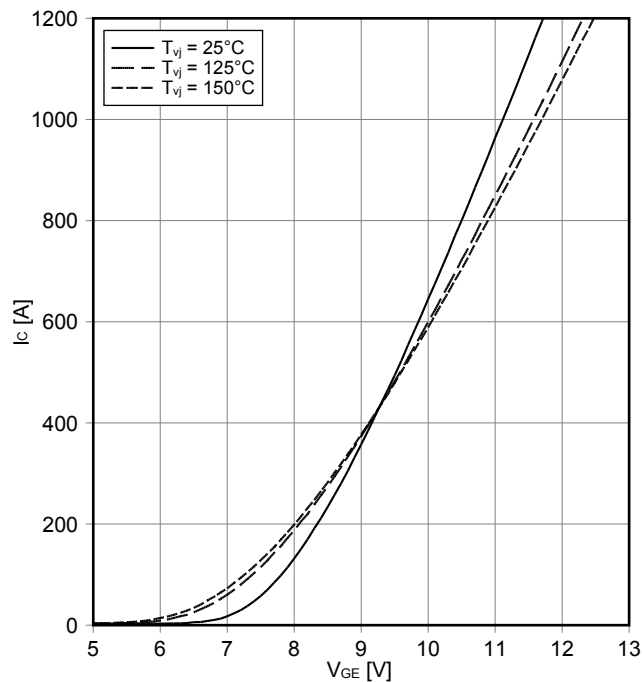
Ausgangskennlinienfeld IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



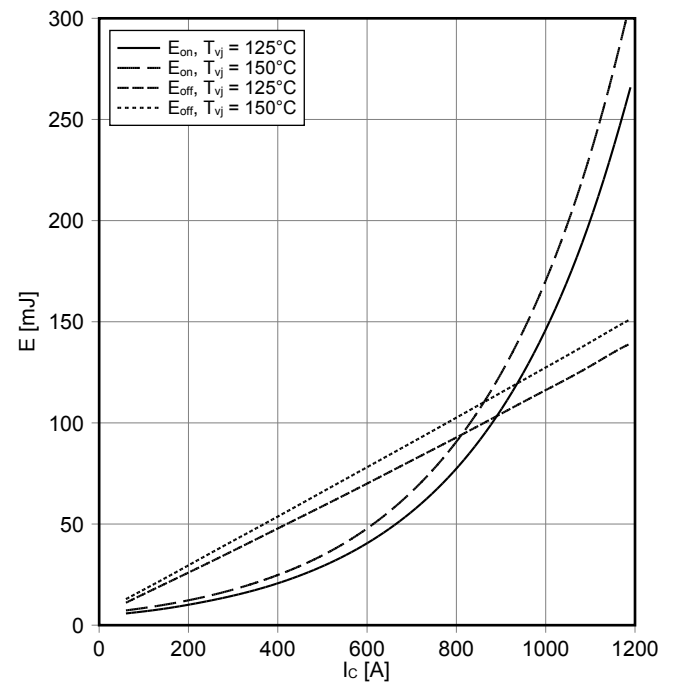
Übertragungscharakteristik IGBT, Wechselrichter (typisch)
transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)

$E_{on} = f(I_C), E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 0.51\ \Omega, R_{Goff} = 0.51\ \Omega, V_{CE} = 600\text{ V}$

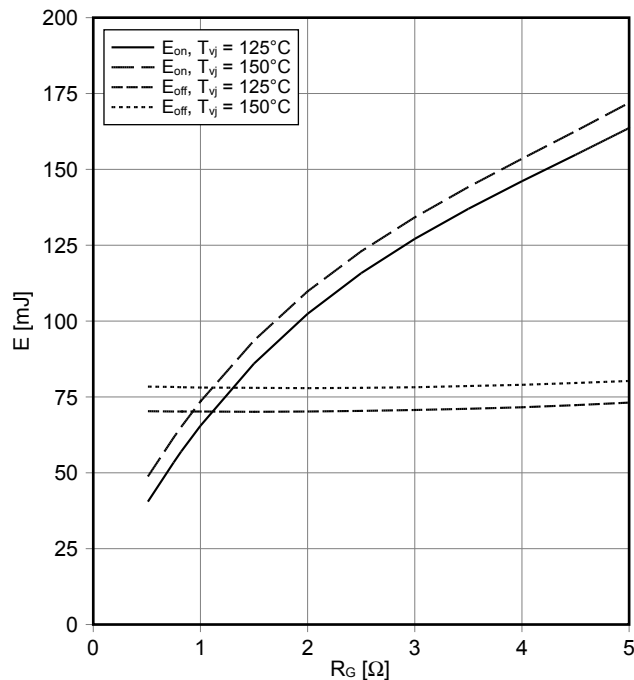


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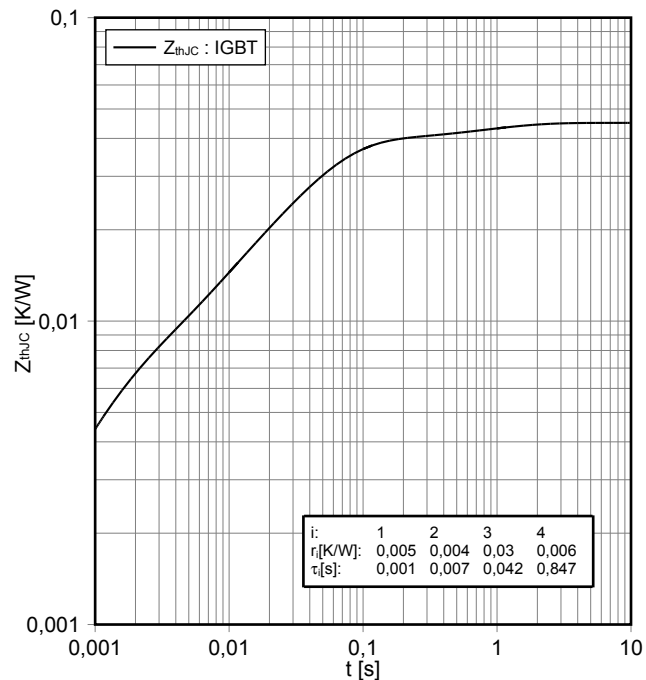
Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}$, $I_C = 600\text{ A}$, $V_{CE} = 600\text{ V}$



Transienter Wärmewiderstand IGBT, Wechselrichter
transient thermal impedance IGBT, Inverter

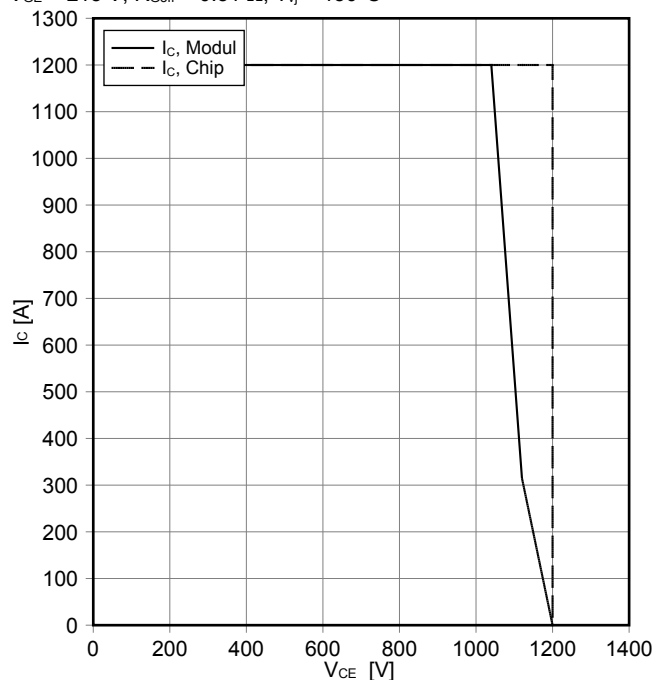
$Z_{thJC} = f(t)$



Sicherer Rückwärts-Arbeitsbereich IGBT, Wechselrichter
(RBSOA)

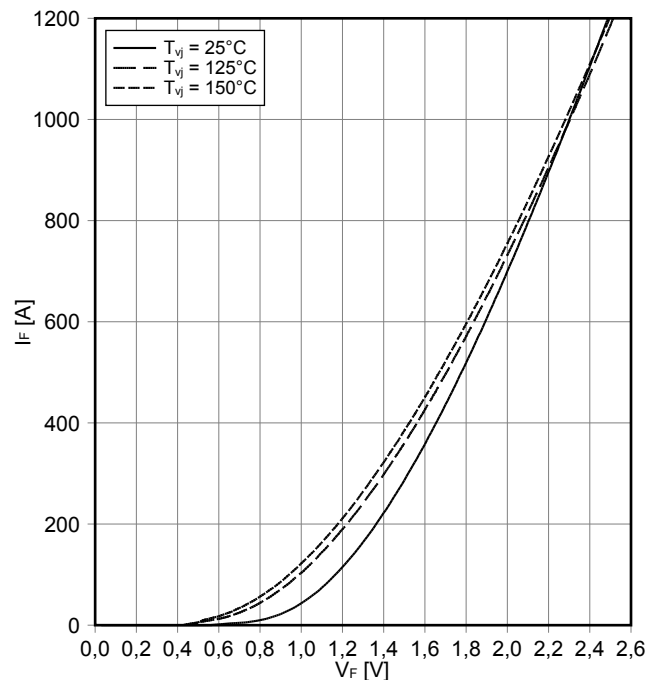
reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 0.51\ \Omega$, $T_{vj} = 150^\circ\text{C}$



Durchlasskennlinie der Diode, Wechselrichter (typisch)
forward characteristic of Diode, Inverter (typical)

$I_F = f(V_F)$

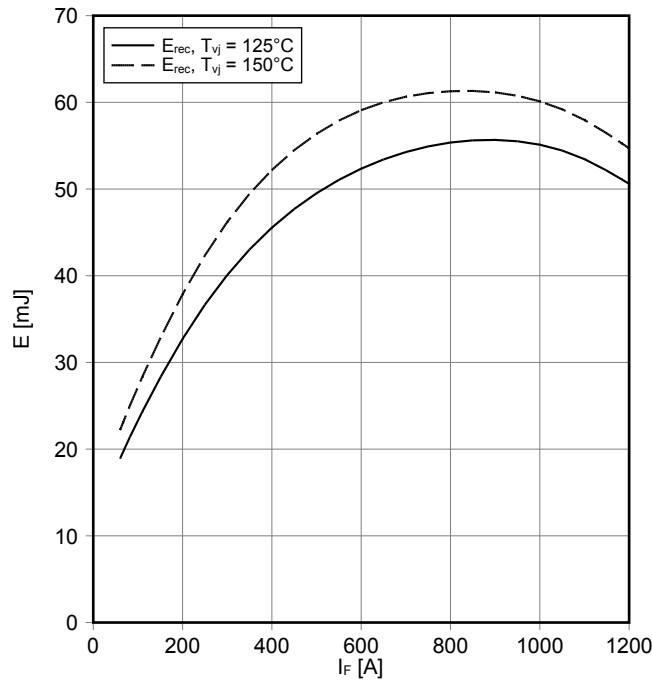


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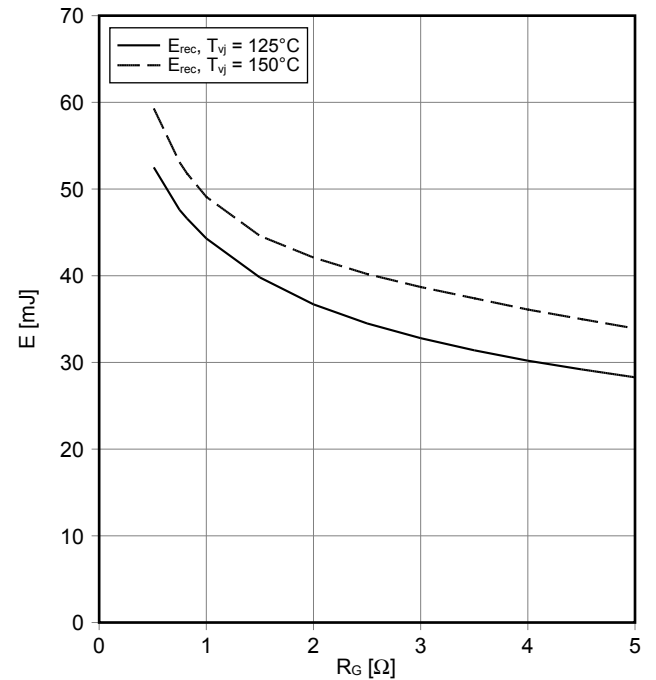
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 0.51 \Omega, V_{CE} = 600 V$



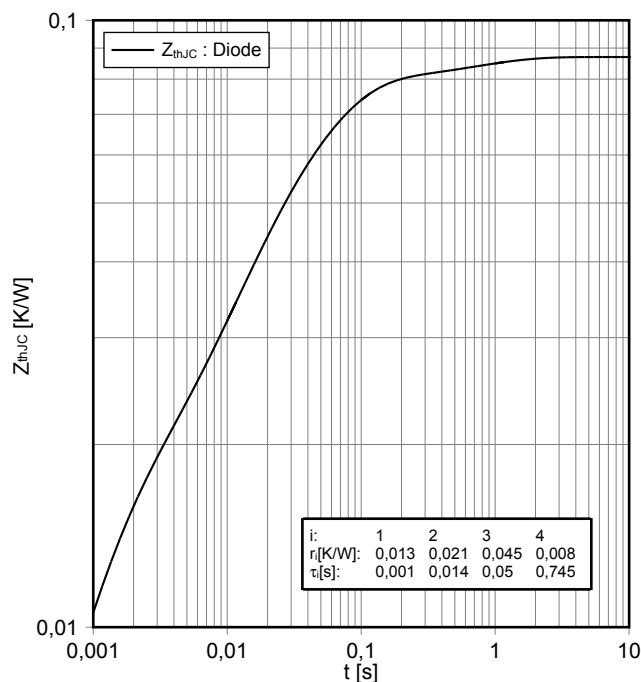
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 600 A, V_{CE} = 600 V$



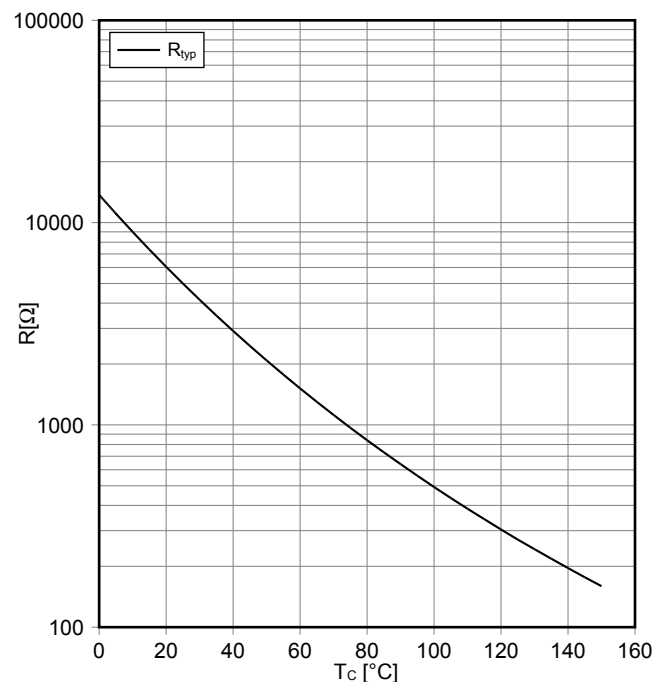
Transienter Wärmewiderstand Diode, Wechselrichter
transient thermal impedance Diode, Inverter

$Z_{thJC} = f(t)$



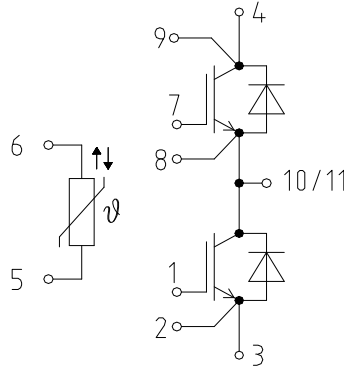
NTC-Widerstand-Temperaturkennlinie (typisch)
NTC-Thermistor-temperature characteristic (typical)

$R = f(T)$

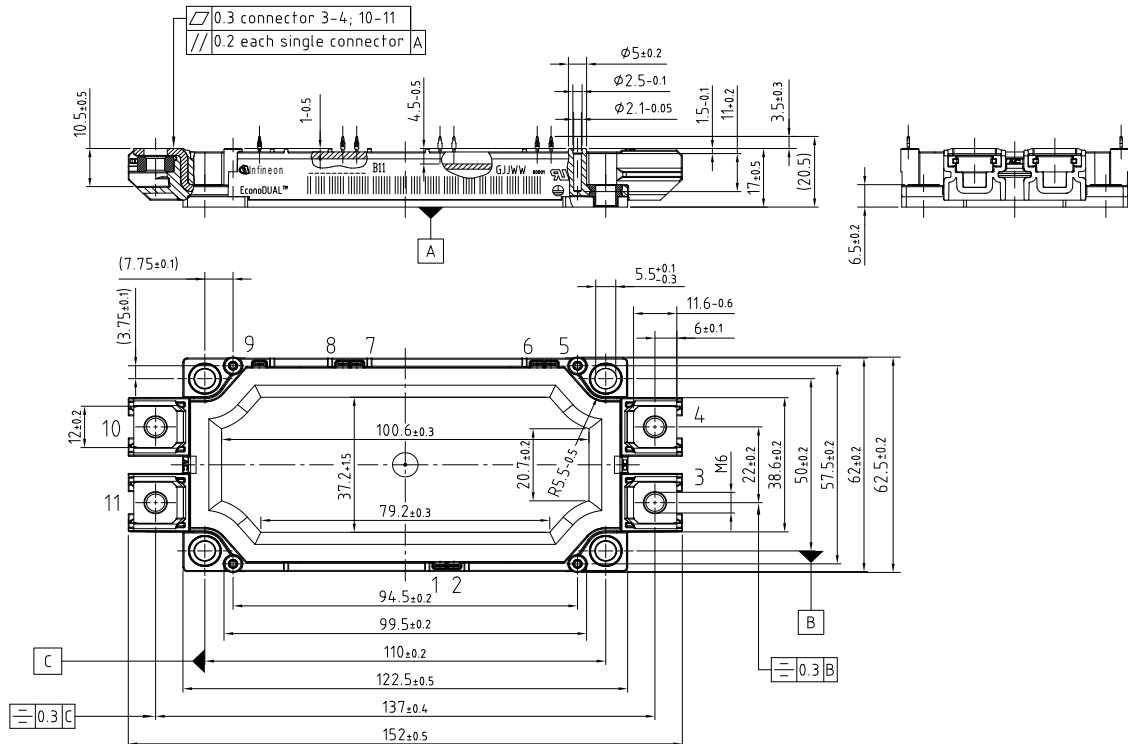


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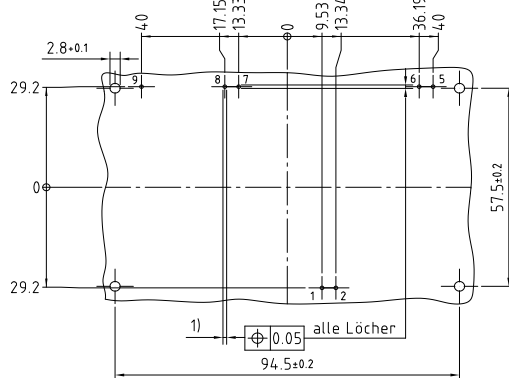
Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines



Leiterplatten-Lochbild / PCB drillhole pattern



- 1) $\phi 1.0_{-0.09}^{+0.09}$ Durchmesser des metallierten Loches
- $\phi 1.0_{-0.06}^{+0.06}$ Diameter of finished plated-through hole
- $\phi 1.15$ Bohrungsdurchmesser des Loches
- $\phi 1.15$ Diameter of drilled hole

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